

# NCE P-Channel Enhancement Mode Power MOSFET

# **Description**

The NCE4963 uses advanced trench technology to provide excellent  $R_{\rm DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications.

### **General Features**

•  $V_{DS} = -20V, I_{D} = -7A$ 

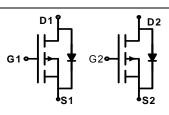
 $R_{DS(ON)}$  < 27m $\Omega$  @  $V_{GS}$ =-4.5V

 $R_{DS(ON)}$  < 39m $\Omega$  @  $V_{GS}$ =-2.5V

- High power and current handing capability
- Lead free product is acquired
- Surface Mount Package

# **Application**

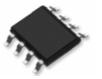
- Motor drive
- Load switch
- Power management



#### Schematic diagram



Marking and pin assignment



SOP-8 top view

# **Package Marking And Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
4963	NCE4963	SOP-8	Ø330mm	12mm	2500 units

# Absolute Maximum Ratings (T<sub>A</sub>=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	-20	V	
Gate-Source Voltage	V <sub>GS</sub>	±12	V	
Drain Current-Continuous	I <sub>D</sub>	-7	Α	
Drain Current-Pulsed (Note 1)	I <sub>DM</sub>	-40	Α	
Maximum Power Dissipation	P <sub>D</sub>	3.0	W	
Operating Junction and Storage Temperature Range	$T_{J}$ , $T_{STG}$	-55 To 150	$^{\circ}$	

### **Thermal Characteristic**

Thermal Resistance, Junction-to-Ambient (Note 2)	R <sub>θJA</sub>	42	°C/W
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# Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =-250μA	-20	-	-	V



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# NCE4963

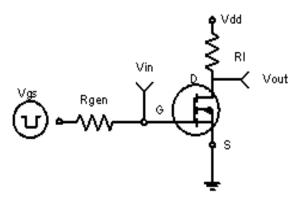
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-20V,V <sub>GS</sub> =0V	-	-	-1	μA	
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±12V,V <sub>DS</sub> =0V		-	±100	nA	
On Characteristics (Note 3)							
Gate Threshold Voltage	$V_{GS(th)}$	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =-250μA	-0.6	-0.8	-1.4	V	
	Б	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-6.5A	-	21	27	mΩ	
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-5A	-	29	39	mΩ	
Forward Transconductance	<b>g</b> FS	$V_{DS}$ =-5 $V$ , $I_{D}$ =3 $A$	-	10	-	S	
Dynamic Characteristics (Note4)							
Input Capacitance	C <sub>lss</sub>	V <sub>DS</sub> =-10V.V <sub>GS</sub> =0V.	-	2100	-	PF	
Output Capacitance	C <sub>oss</sub>	F=1.0MHz	-	450	-	PF	
Reverse Transfer Capacitance	C <sub>rss</sub>	1 - 1.0IVII 12		300	-	PF	
Switching Characteristics (Note 4)							
Turn-on Delay Time	t <sub>d(on)</sub>		-	25	-	nS	
Turn-on Rise Time	t <sub>r</sub>	V <sub>DD</sub> =-10V, ID=-1A,	-	30	-	nS	
Turn-Off Delay Time	$t_{d(off)}$	$V_{GS}$ =-4.5 $V$ , $R_{GEN}$ =6 $\Omega$	-	70	-	nS	
Turn-Off Fall Time	t <sub>f</sub>		-	50	-	nS	
Total Gate Charge	Qg		-	17	-	nC	
Gate-Source Charge	$Q_{gs}$	$V_{DS}$ =-10V, $I_{D}$ =-6.5A, $V_{GS}$ =-4.5V	-	4.1	-	nC	
Gate-Drain Charge	Q <sub>gd</sub>		-	4.3	-	nC	
Drain-Source Diode Characteristics							
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =-7A	-	-	-1.2	V	

# Notes:

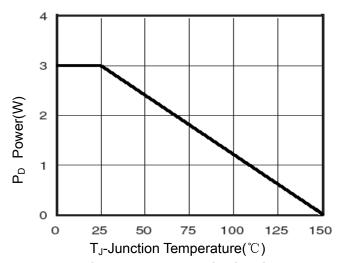
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production



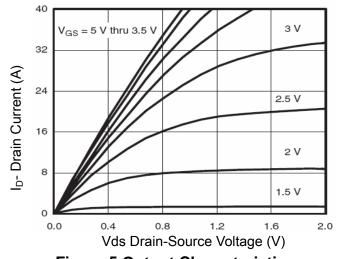
# **Typical Electrical and Thermal Characteristics**



**Figure 1 Switching Test Circuit** 



**Figure 3 Power Dissipation** 



**Figure 5 Output Characteristics** 

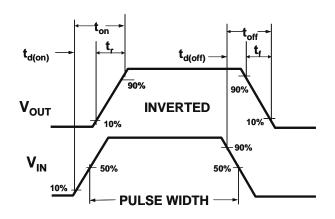
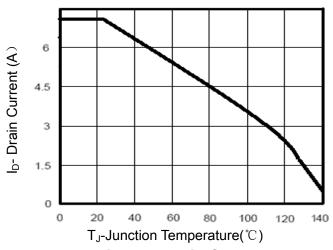


Figure 2 Switching Waveforms



**Figure 4 Drain Current** 

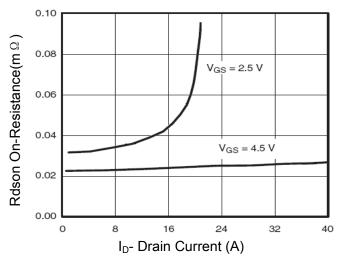
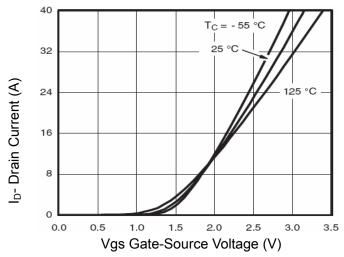


Figure 6 Drain-Source On-Resistance





**Figure 7 Transfer Characteristics** 

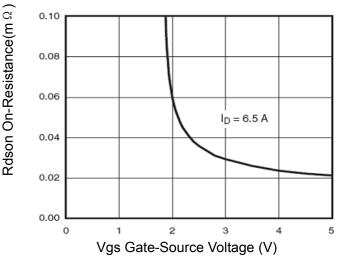


Figure 9 Rdson vs Vgs

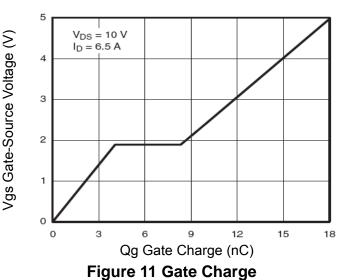


Figure 8 Drain-Source On-Resistance

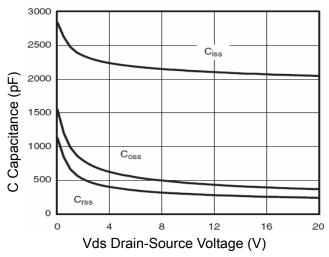


Figure 10 Capacitance vs Vds

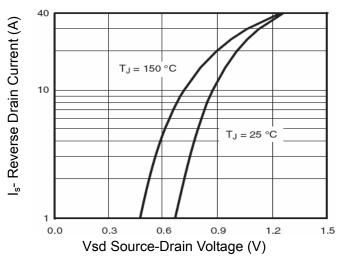


Figure 12 Source- Drain Diode Forward



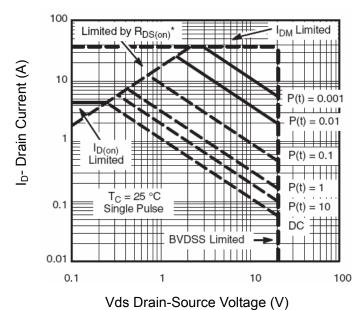
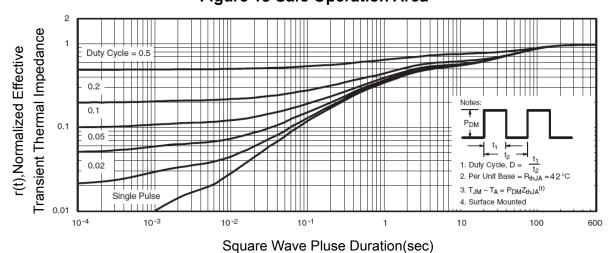


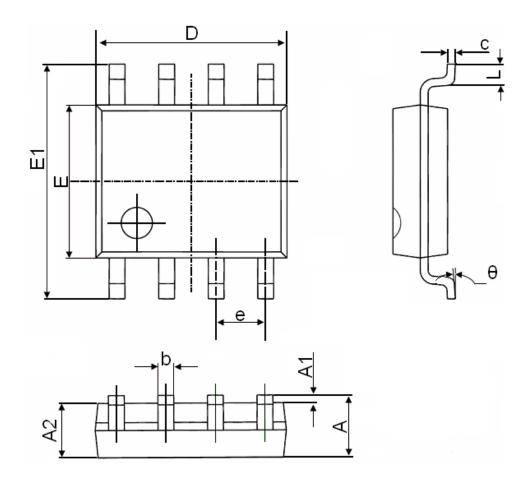
Figure 13 Safe Operation Area



**Figure 14 Normalized Maximum Transient Thermal Impedance** 

**Pb Free Product** 

# **SOP-8 Package Information**



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
С	0.170	0.250	0.006	0.010	
D	4.700	5.100	0.185	0.200	
E	3.800	4.000	0.150	0.157	
E1	5.800	6.200	0.228	0.244	
е	1.270	(BSC)	0.050	(BSC)	
L	0.400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	



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NCE4963

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